

BGA-936A BGA Rework Station



- SMART** New Fuzzy Industrial Microprocessor
- ACCURATE** Different Color Alignment System
- EFFICIENCY** Ultra Large Preheating Zone
- SUPER FINE** Automatic Mechanism and Durable Structure

New page to BGA Rework equipments. BGA-936A is specially designed for R&D and RMA department in computer and communication fields. Not only brings operators working pleasure from soldering and desoldering procedures but also more economical, higher efficient solution.

With the assistance of Industrial Microprocessor, no more tools and PC needed. Users can directly set up temperature profile, auto-cooling, auto pick-up, profile print-out and adjust related parameters according to varied condition.

From cell phone to Server PCB, BGA-936A offers excellent flexibility and performance. Confirmation and support from PCB manufacturers over all the world make us believe BGA-936A will also be your best choice!

Fast Chip Feed-in



Auto Chip Pick-up



Different Color Alignment System



Auto Reflow



Auto Quick Cooling Device



SMART New Fuzzy Industrial Microprocessor

New Fuzzy Industrial Microprocessor System with FDD Data Storage

PC-based Industry-Level Microprocessor System and LCD panel, more accurate and stable operation. All the parameter and heating process can be recorded without extra PC or equipment connection.

Auto Pick-UP vacuum function makes Reflow / Desoldering of BGA and LLP chips easier. Design for independent operation, profile can be printed out directly as well as via built-in Rs232 connect to computer.

Smart Operation Control Box



All parameter can be directly settled in the LCD panel without using any other facility. Also equipped with extra removable controller for easy operation.

All soldering parameter can be saved, installed and printed with FDD.

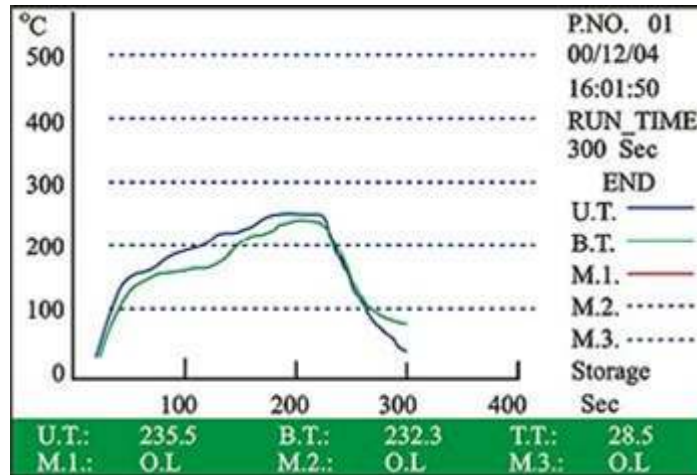
PROGRAM	1	2	3	NAME	12345678
STEP	1	2	3	4	5 6
UP_HEAT	150	180	215	225	235 235
BTM_HEAT	150	180	215	225	230 230
OUTPUT %	100	100	100	100	100 100
TIME SEC	40	40	30	30	40 50
AIRFLOW	5	5	5	5	5 5
COOLING	0	0	0	0	0 0
PICK_UP	0	0	0	0	0
0PROG_SAVE	SAVE			TEMP_UNIT	°C
DATE: 00/12/04 16:01:50					
STATE	END	U.T.	235.5	M.1	O.L
RUN	300 Sec	B.T.	232.3	M.2	O.L
STAY	0 Sec	E.T.	28.5	M.3	O.L

Clear Temperature Parameter List

Profile Direct Show-up for 99 sets and unlimited profiles space

Fast check on 99 sets of profile memory : completely solves the profile reset problem caused by the difference of BGA chips. Save operation time and enhance production efficiency.

Unlimited sets of profiles space : Besides fast check function, Operators can install as many as temperature profile on BGA-936A via built-in FDD. "Once used, forever memorized." Is our always promise to clients.



Excellent Temperature Profile Setting



Included 3 Temperature Detectors

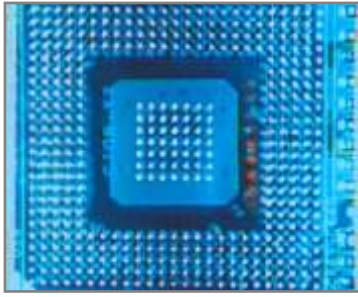
Three Sets of thermocouple can measure the heating characteristic of body of BGA and PC Board directly.

Reflow profile can be 100% set up and operator can easily set up parameter with complicated training course in advance.

Chinese and English language for option.

3 Sets of Temperature detectors

ACCURATE Different Color Alignment System



Bright Color Comparison

Simply overlap the red of solder balls and green of pad into one image.

Different Color Alignment System marks Perfect Image

World No.1 Model created Different Color Alignment System (Patent No : 177479)

Special design for CSP (uBGA, Tiny BGA), fine pitch BGA and LLP.

When images of BGA and PC Board overlap, comparison between two images will be very clear.

Automatically Z spindle and Alignment system : Quick and easy move, accurate location with aviation industrial precision linear motion guide.

The same position mechanism avoid CSP chips moving



The Best Same Position Mechanism

Pick up, alignment and reflow at the same position avoid chips moving.

Auto / manual option for Z spindle. Fully enhance soldering efficiency and easy operation.

Alignment of BGA procedure and soldering work are proceeded at the same position.

No need to do alignment on the right and reflow on the left side.

Completely avoid aligned BGA chips deviation due the movement.

High Precision device for fast BGA chip Location



Best Position by BGA chip Location device

Completely avoid the position difference caused by manual operation.

Fast, safe, efficient solution.

No more solder paste trouble resulted from direct contact with hand.

Best recision even long term continuous usage.

No need to adjust X, Y shafts at all.

EFFICIENCY Ultra Large Preheating Zone



Super Size Preheating Heater with 3 Zone

Rapid disassembly and soldering, increase 50% efficiency.

Preheating area : 360 x 260 mm and able to divide into 3 zones to satisfy the need for different-size PCB.

Preheating zones can be operated synchronously or independently.

Completely solve bend / cock problem caused by uneven / tiny preheating.

Module design : low cost for maintenance and repair.

Ultra Larger Preheating Zone

Shorten preheating time and offers big and evenly preheating to all PCB.

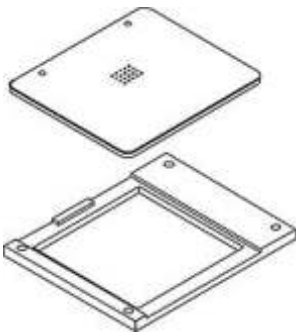
Quick Cooling System Provides high efficiency



Drastically reduce cooling time by 50% than other designs.
Work with electricity and no extra air compressor needed.
Built-in auto cooling device highly improve 50% working efficiency.

Auto Quick Cooling Device
Improve 50% efficiency.

High Precision LLP Chip Solder Paste-Printing device



Average printing time for one BGA / LLP chip is within 30 seconds.
Able to locate Printing fixture on alignment system directly for perfect alignment effect.
Unified Flux thickness from Solder Paste-Paste Printing device helps users has best reflow quality.
Qualify for CE and MIL standard.

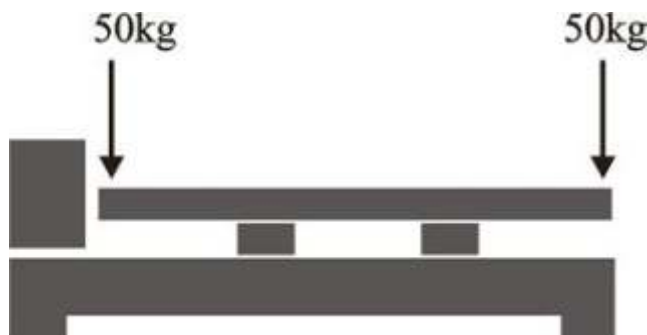
SUPER FINE Automatic Mechanism and Durable Structure



Automatic Mechanism Save time and manpower

Z shift and CCD camera: directly controlled by Microprocessor or Z shift control box aside.
User-friendly design: no more damage due to wrong operation in CCD camera system.
Alignment system will automatically turn off while Z axis going down.

Durable Structure and Modular designed for Easy Maintenance



Durable structure design: Even put 50 kg heavy stuff on either side of PCB clamber, no shake will happen.
Advanced linear motion guide: Not only make X/Y tables movement more smoothly but make whole structure more durable

Designed for Lead-Free Soldering

Completely solve lead-free rework process strict requirement.
High efficiency Nitrogen reflow system for option.

A) OPEN HALL (OH)

B) CLOSE HALL (CH)

C) SOJ.PLCC

D) DIP.PGA


The BGA 936A suits every type of BGA& SMD, Only needs to change the nozzle.

BGA/CSP/LLP				SOP.QFP			
NO.	SIZE	TYPE		NO.	SIZE	TYPE	
		OH	CH			OH	CH
BGA-N001	5X5		jE	BGA-N041	13X12		jE
BGA-N004	5X10		jE	BGA-N043	13X20		jE
BGA-N007	10X10		jE	BGA-N045	15X22		jE
BGA-N008	10X12		jE	BGA-N047	17X30		jE
BGA-N010	10X15		jE	BGA-N051	11X11		jE
BGA-N013	20X20		jE	BGA-N052	13X13		jE
BGA-N016	16X24		jE	BGA-N053	15X15		jE
BGA-N020	29X29	jE		BGA-N054	17X17		jE
BGA-N022	32X32	jE		BGA-N055	19X19		jE
BGA-N024	37X37	jE		BGA-N056	21X21		jE
BGA-N025	39X39	jE		BGA-N057	23X23		jE
BGA-N026	42X42			BGA-N058	25X25		jE
BGA-N028	45X45	jE		BGA-N059	26X20		jE
BGA-N029	55X45			BGA-N061	33X33		jE
BGA-N030	70X70	jE		BGA-N062	35X35		jE
BGA-N031	62X57						
BGA-N032	60X20						

SOJ.PLCC

NO.	SIZE	TYPE	
		OH	CH
BGA-N081	10X17		jE
BGA-N083	12X19		jE
BGA-N085	12X27		jE
BGA-N090	12X12		jE
BGA-N091	14X14		jE
BGA-N093	17X15		jE
BGA-N095	20X20		jE
BGA-N096	25X25		jE
BGA-N097	27X27		jE
BGA-N098	32X32		jE
BGA-N099	37X37		jE
BGA-N147	49X49		jE

DIP-PGA

NO.	SIZE	TYPE	
		OH	CH
BGA-N121	10X20		jE
BGA-N122	10X22.5		jE
BGA-N123	10X25		jE
BGA-N124	10X27.5		jE
BGA-N131	18X32		jE
BGA-N133	18X37		jE
BGA-N135	18X42		jE
BGA-N139	18X52		jE
BGA-N141	21.5X21.5		jE
BGA-N143	29X29		jE
BGA-N145	34X34		jE